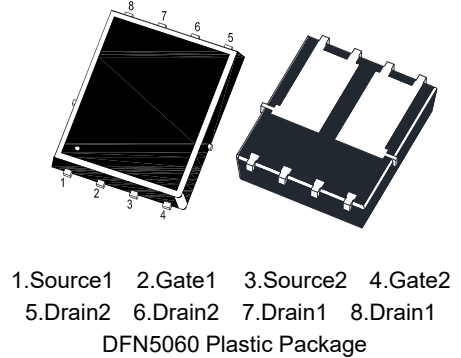
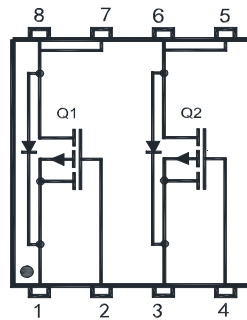


WTM603P260L-AH

Dual P-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- Low On-Resistance
- Low Input Capacitance
- Low Miller Charge
- Low Input/Output Leakage
- Halogen and Antimony Free(HAF), RoHS compliant



Applications

- Load Switch
- Automotive Systems
- Motor / Body Load Control
- DC-DC converters and Off-line UPS

Key Parameters

Parameter	Value	Unit
$-BV_{DS}$	30	V
$R_{DS(ON)} \text{ Max}$	27 @ $-V_{GS} = 10 \text{ V}$	m Ω
	45 @ $-V_{GS} = 4.5 \text{ V}$	m Ω
$-V_{GS(th)} \text{ typ}$	1.4	V
$Q_g \text{ typ}$	22 @ $-V_{GS} = 10 \text{ V}$	nC

Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified) (Q1/Q2)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$-V_{DS}$	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	$-I_D$	30	A
$T_c = 25^\circ\text{C}$		19	
$T_c = 100^\circ\text{C}$			
Peak Drain Current, Pulsed ¹⁾	$-I_{DM}$	90	A
Single-Pulse Avalanche Current	$-I_{AS}$	23	A
Single-Pulse Avalanche Energy ²⁾	E_{AS}	26	mJ
Power Dissipation	P_D	41	W
$T_c = 25^\circ\text{C}$			
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$

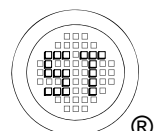
Thermal Characteristics (Q1/Q2)

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3	$^\circ\text{C/W}$
Thermal Resistance from Junction to Ambient ³⁾	$R_{\theta JA}$	43	$^\circ\text{C/W}$

¹⁾ Pulse Test: Pulse Width $\leq 100 \mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.

²⁾ Limited by $T_{J(MAX)}$, starting $T_J = 25^\circ\text{C}$, $L = 0.1 \text{ mH}$, $R_g = 25 \Omega$, $-I_D = 23 \text{ A}$, $V_{GS} = 10 \text{ V}$.

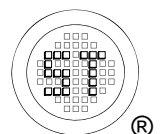
³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



WTM603P260L-AH

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified (Q1/Q2)

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $-I_D = 250\ \mu\text{A}$	$-BV_{DSS}$	30	-	-	V
Drain-Source Leakage Current at $-V_{DS} = 30\ \text{V}$	$-I_{DSS}$	-	-	1	μA
Gate Leakage Current at $V_{GS} = \pm 20\ \text{V}$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at $V_{DS} = V_{GS}$, $-I_D = 250\ \mu\text{A}$	$-V_{GS(th)}$	1	-	2.5	V
Drain-Source On-State Resistance at $-V_{GS} = 10\ \text{V}$, $-I_D = 9.1\ \text{A}$ at $-V_{GS} = 4.5\ \text{V}$, $-I_D = 6.9\ \text{A}$	$R_{DS(on)}$	- -	23 -	27 45	m Ω
DYNAMIC PARAMETERS					
Gate Resistance at $V_{DS} = 0\ \text{V}$, $V_{GS} = 0\ \text{V}$, $f = 1\ \text{MHz}$	R_g	-	4.5	-	Ω
Forward Transconductance at $-V_{DS} = 10\ \text{V}$, $-I_D = 9.1\ \text{A}$	g_{fs}	-	10	-	S
Input Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $f = 1\ \text{MHz}$	C_{iss}	-	1277	-	pF
Output Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $f = 1\ \text{MHz}$	C_{oss}	-	121	-	pF
Reverse Transfer Capacitance at $V_{GS} = 0\ \text{V}$, $-V_{DS} = 15\ \text{V}$, $f = 1\ \text{MHz}$	C_{rss}	-	84	-	pF
Total Gate Charge at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$ at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 4.5\ \text{V}$	Q_g	- -	22 10	- -	nC
Gate Source Charge at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$	Q_{gs}	-	5	-	nC
Gate Drain Charge at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$	Q_{gd}	-	3	-	nC
Turn-On Delay Time at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$, $R_g = 3.3\ \Omega$	$t_{d(on)}$	-	10	-	ns
Turn-On Rise Time at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$, $R_g = 3.3\ \Omega$	t_r	-	24	-	ns
Turn-Off Delay Time at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$, $R_g = 3.3\ \Omega$	$t_{d(off)}$	-	15	-	ns
Turn-Off Fall Time at $-V_{DS} = 15\ \text{V}$, $-I_D = 9.1\ \text{A}$, $-V_{GS} = 10\ \text{V}$, $R_g = 3.3\ \Omega$	t_f	-	2.5	-	ns
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at $-I_S = 1\ \text{A}$, $V_{GS} = 0\ \text{V}$	$-V_{SD}$	-	-	1.3	V
Body-Diode Continuous Current	$-I_S$	-	-	30	A
Body-Diode Continuous Current, Pulsed	$-I_{SM}$	-	-	90	A
Body Diode Reverse Recovery Time at $-I_S = 9.1\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	t_{rr}	-	10.5	-	ns
Body Diode Reverse Recovery Charge at $-I_S = 9.1\ \text{A}$, $di/dt = 100\ \text{A} / \mu\text{s}$	Q_{rr}	-	4.4	-	nC



Electrical Characteristics Curves (Q1/Q2)

Fig. 1 Typical Output Characteristic

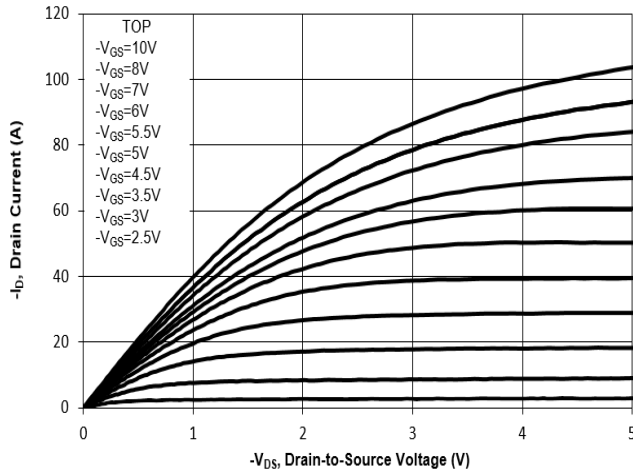


Fig. 2 Typical Transfer Characteristic

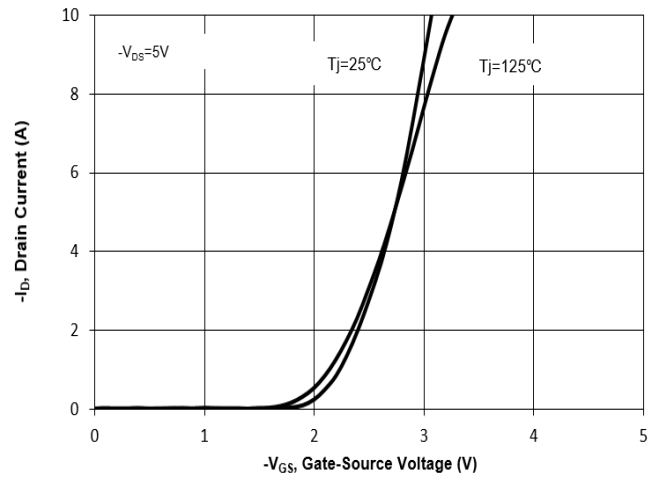


Fig. 3 On-Resistance vs. Drain Current

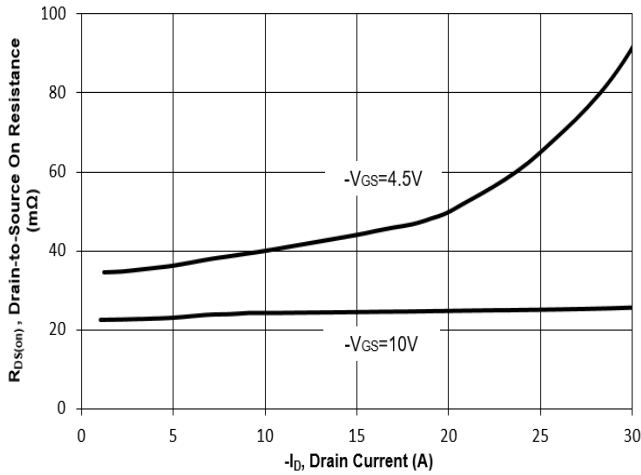


Fig. 4 on-Resistance vs. Gate Voltage

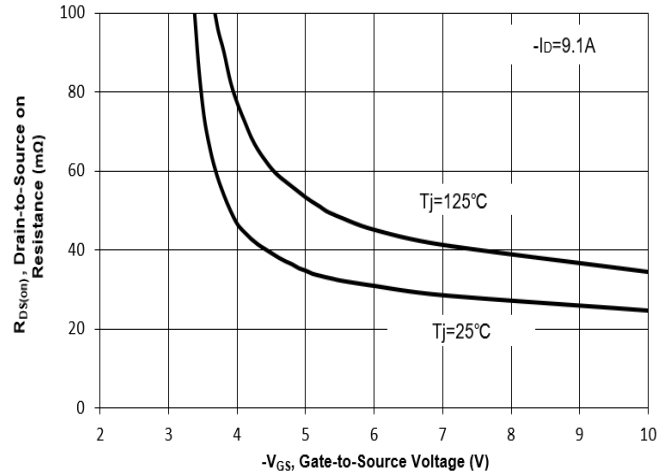


Fig. 5 on-Resistance vs. TJ

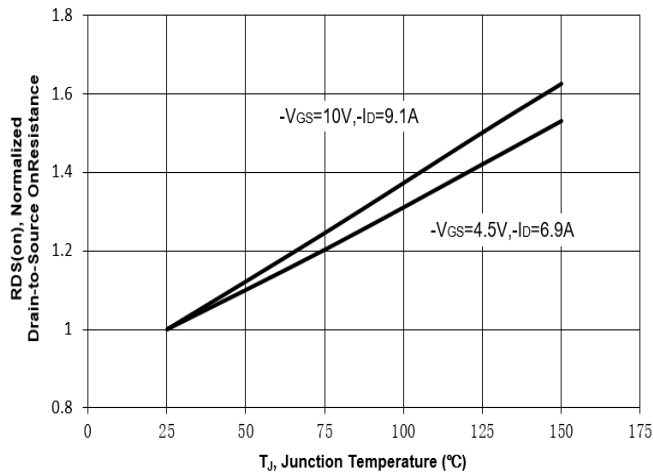
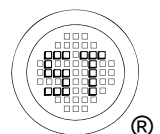
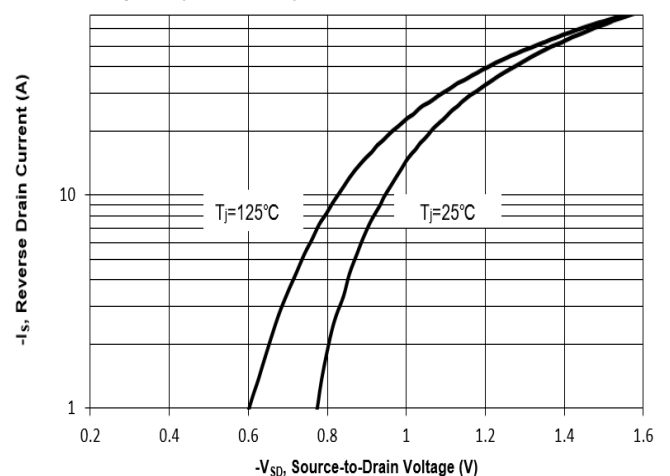


Fig. 6 Typical Body Diode Forward Characteristic



Electrical Characteristics Curves (Q1/Q2)

Fig. 7 Typical Junction Capacitance

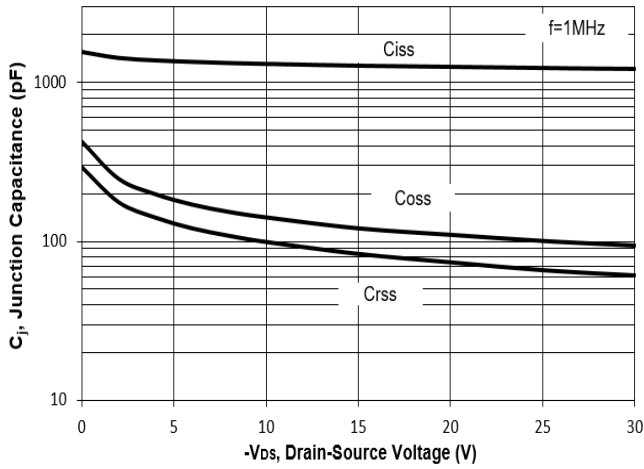


Fig. 8 Drain-Source Leakage Current vs. T_j

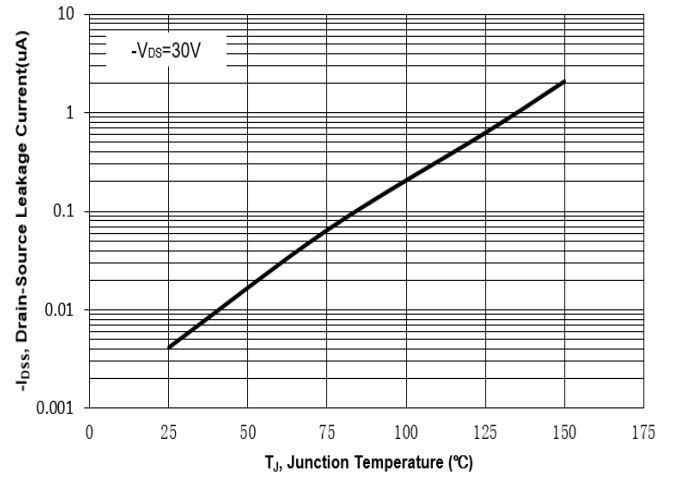


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

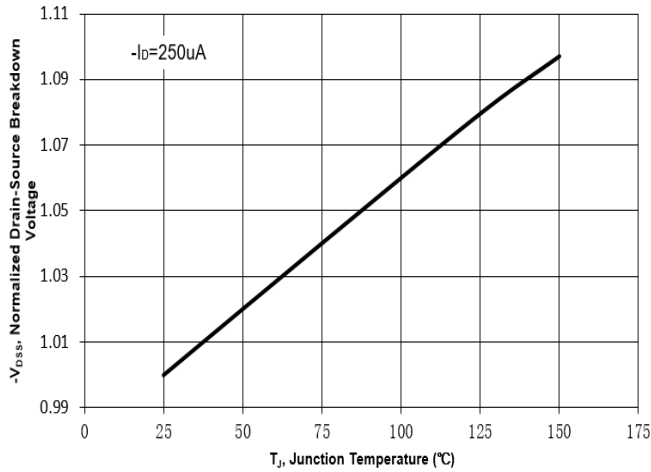


Fig. 10 Gate Threshold Variation vs. T_j

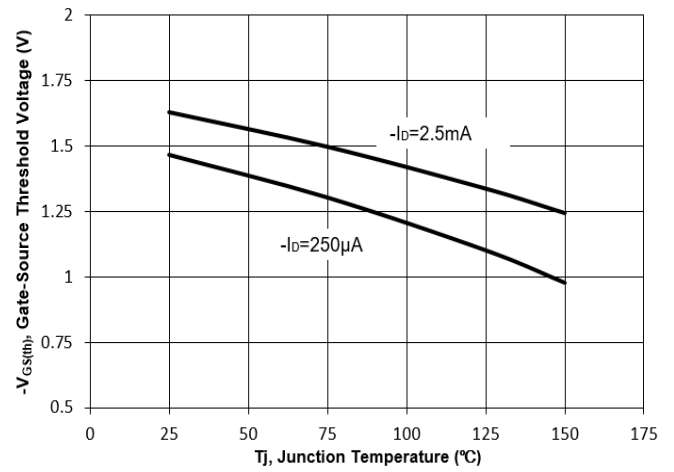


Fig. 11 Gate Charge

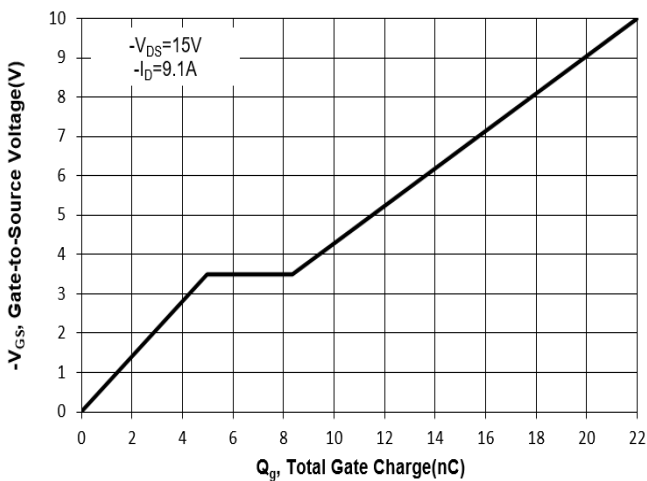
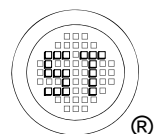
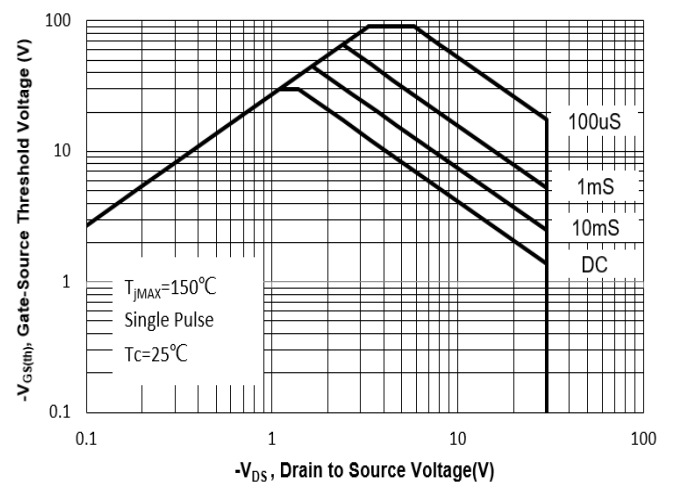


Fig. 12 Safe Operation Area



Electrical Characteristics Curves (Q1/Q2)

Fig. 13 Normalized Maximum Transient Thermal Impedance($Z_{\theta JC}$)

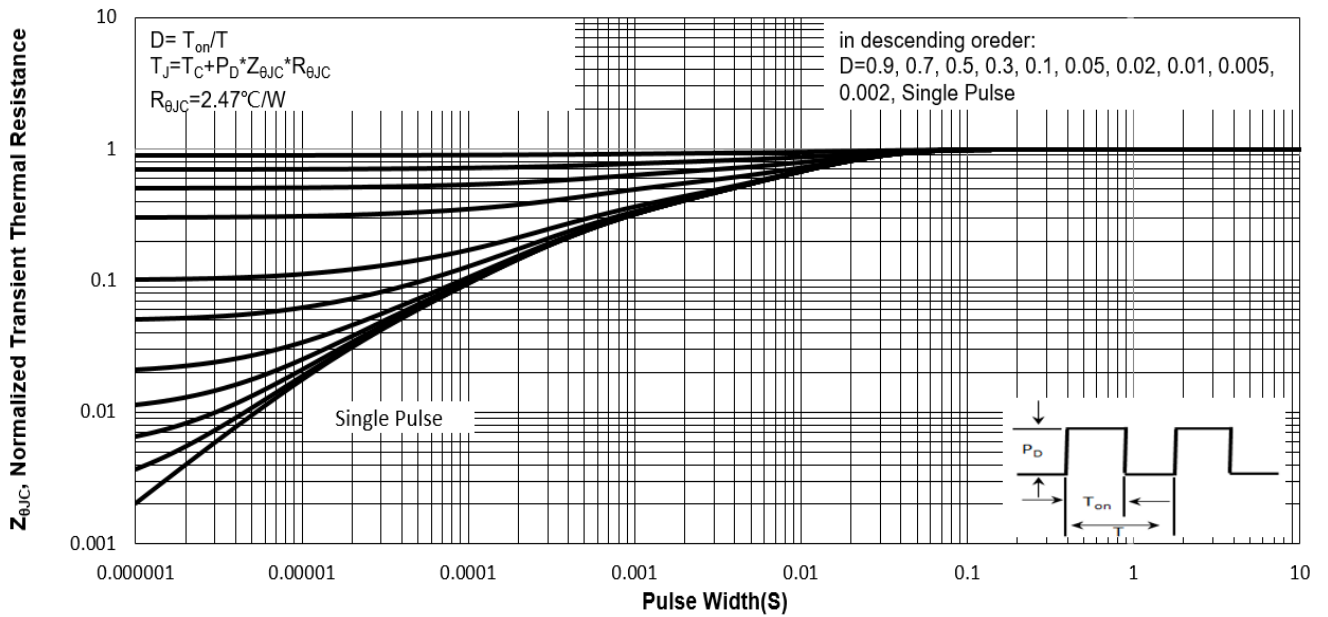
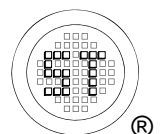
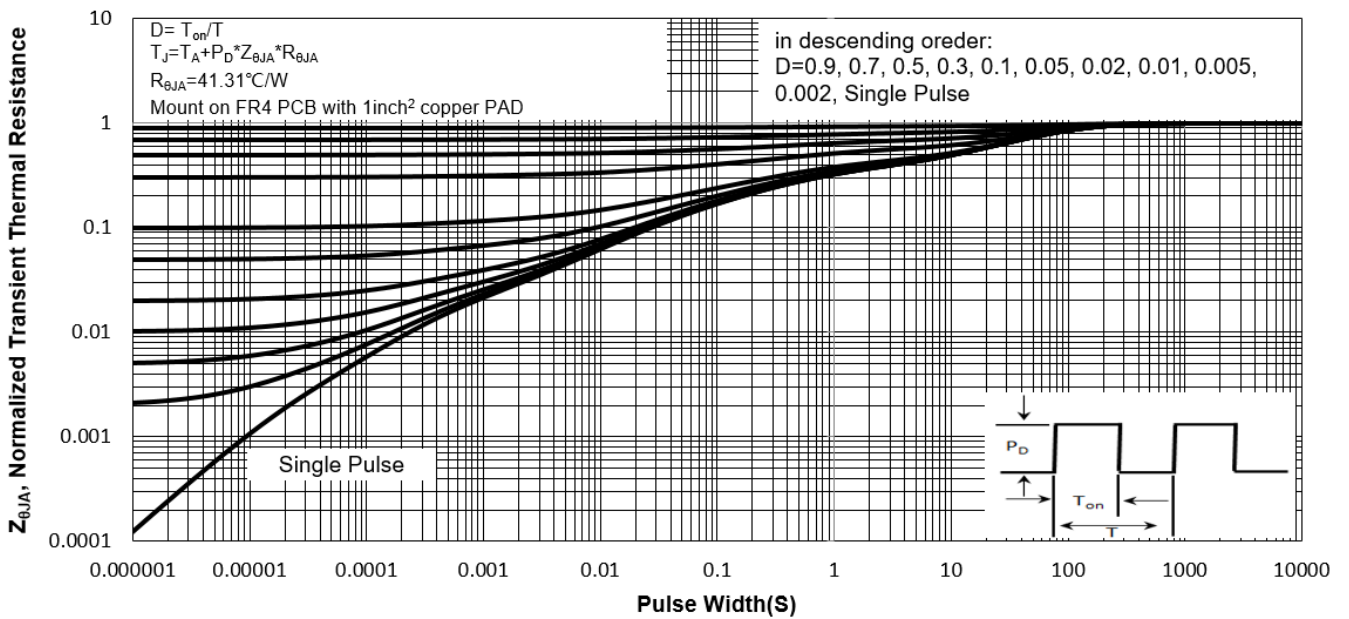


Fig. 14 Normalized Maximum Transient Thermal Impedance($Z_{\theta JA}$)



Test Circuits (Q1/Q2)

Fig.1-1 Switching times test circuit

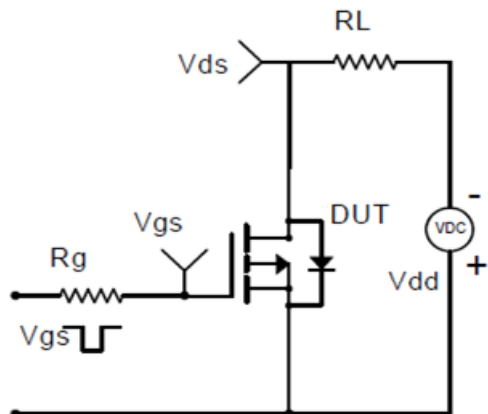


Fig.1-2 Switching Waveform

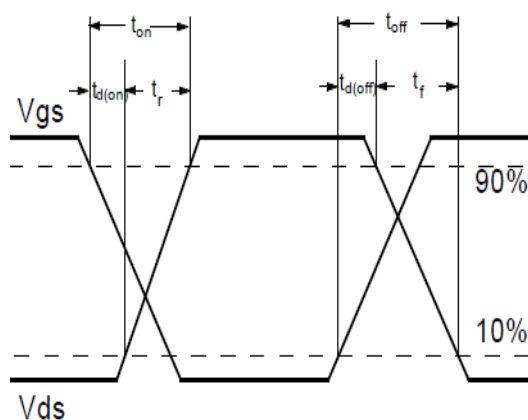


Fig.2-1 Gate charge test circuit

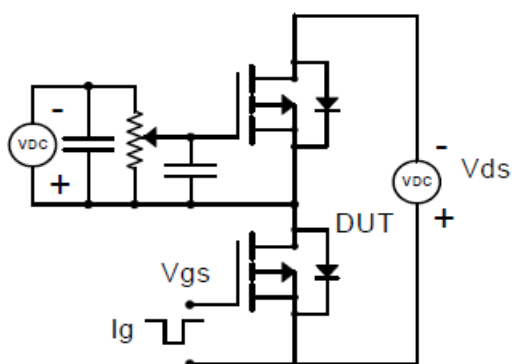


Fig.2-2 Gate charge waveform

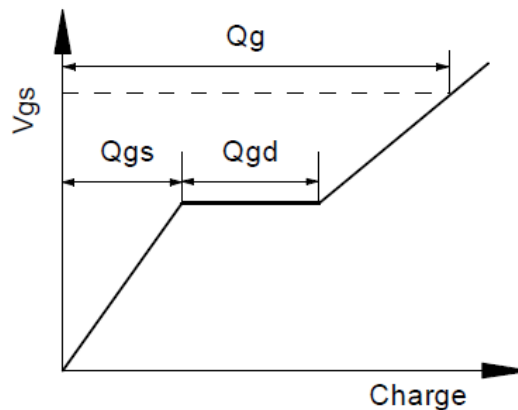


Fig.3-1 Avalanche test circuit

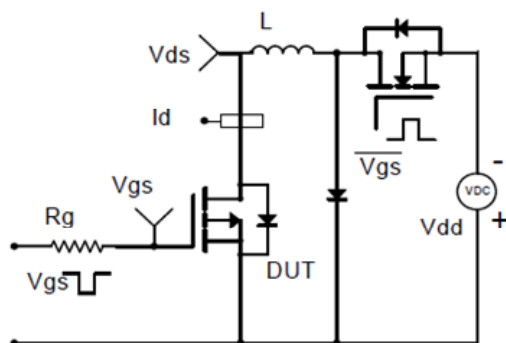
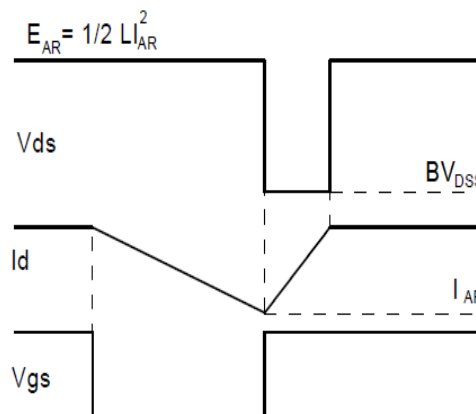


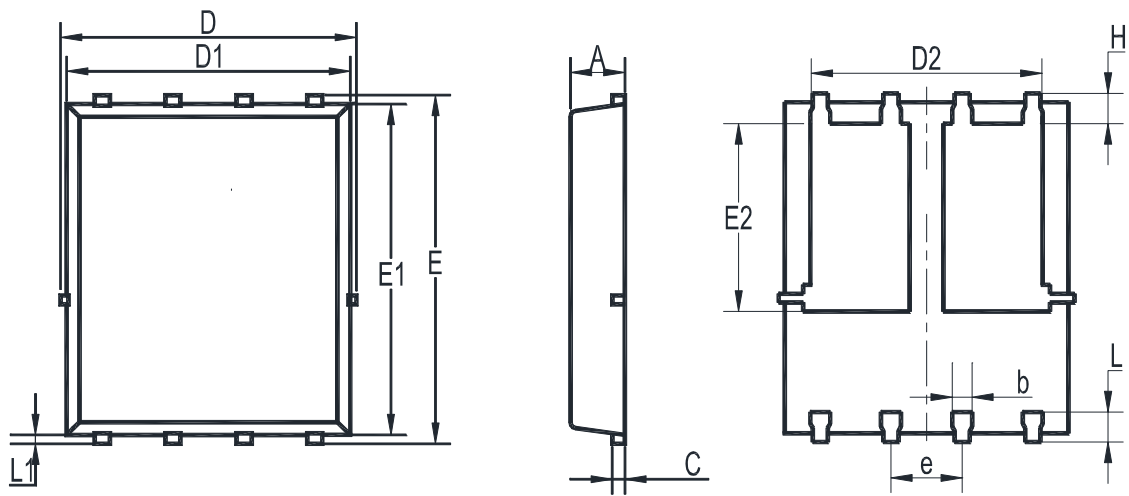
Fig.3-2 Avalanche waveform



WTM603P260L-AH

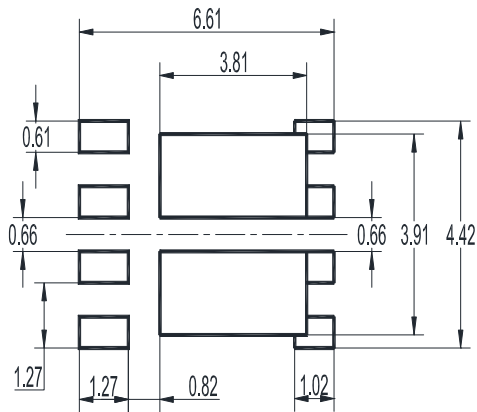
Package Outline Dimensions (Units: mm)

DFN5060



UNIT	A	b	C	D	D1	D2	E	E1	E2	e	L	L1	H
mm	1.12	0.51	0.34	5.26	5.1	4.5	6.25	6	3.66	1.37	0.71	0.2	0.71
	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35

Recommended Soldering Footprint



Packing information

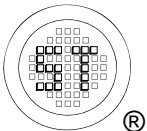
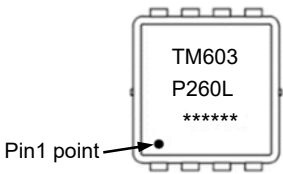
Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN5060	12	8 ± 0.1	0.315 ± 0.004	330	13	3,000

Marking information

" TM603P260L " = Part No

" ***** " = Date Code Marking

Font type: Arial



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